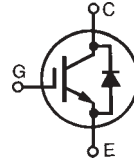


HiPerFAST™ IGBT IXGR 24N60CD1 with Diode ISOPLUS247™ (Electrically Isolated Back Surface)

$$V_{CES} = 600 \text{ V}$$

$$I_{C25} = 42 \text{ A}$$

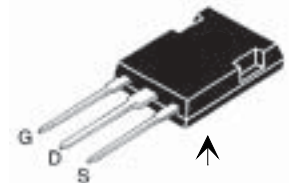
$$V_{CE(sat)} = 2.5 \text{ V}$$



Preliminary data sheet

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_J = 25^\circ\text{C}$ to 150°C	600	V
V_{CGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GE} = 1 \text{ M}\Omega$	600	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ\text{C}$	42	A
I_{C90}	$T_C = 90^\circ\text{C}$	22	A
I_{CM}	$T_C = 25^\circ\text{C}$, 1 ms	80	A
SSOA (RBSOA)	$V_{GE} = 15 \text{ V}$, $T_{VJ} = 125^\circ\text{C}$, $R_G = 22 \Omega$ Clamped inductive load, $L = 100 \mu\text{H}$	$I_{CM} = 48$ @ $0.8 V_{CES}$	A
P_C	$T_C = 25^\circ\text{C}$	80	W
T_J		-55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-55 ... +150	$^\circ\text{C}$
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$
V_{ISOL}		2500	V
Weight	TO-247	6	g

ISOPLUS 247



Isolated back surface*

G = Gate,
E = Emitter

C = Collector

* Patent pending

Features

- Silicon chip on Direct-Copper-Bond substrate
 - High power dissipation
 - Isolated mounting surface
 - 2500V electrical isolation
- Low drain to tab capacitance (<35pF)
- Low $R_{DS(on)}$ HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Fast intrinsic rectifier
- Low gate charge process

Applications

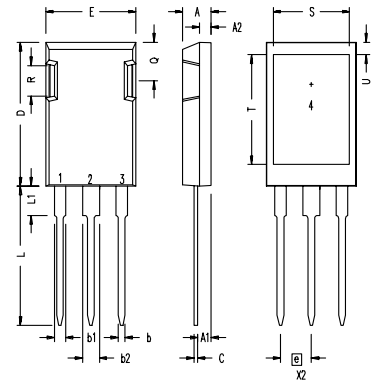
- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control




Advantages

- Easy assembly
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
BV_{CES}	$I_C = 750 \mu\text{A}$, $V_{GE} = 0 \text{ V}$	600		V
$V_{GE(th)}$	$I_C = 250 \mu\text{A}$, $V_{GE} = V_{GE}$	2.5		5.5 V
I_{CES}	$V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0 \text{ V}$		$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	200 μA 3 mA
I_{GES}	$V_{CE} = 0 \text{ V}$, $V_{GE} = \pm 20 \text{ V}$			$\pm 100 \text{ nA}$
$V_{CE(sat)}$	$I_C = I_T$, $V_{GE} = 15 \text{ V}$		2.1	2.5 V

Symbol	Test Conditions	Characteristic Values			
		(T _J = 25°C, unless otherwise specified)			
		min.	typ.	max.	
g_{fs}	I _C = I _T ; V _{CE} = 10 V, Pulse test, t ≤ 300 μs, duty cycle ≤ 2 %	9	17	S	
C_{ies}	V _{CE} = 25 V, V _{GE} = 0 V, f = 1 MHz		1500	pF	
C_{oes}			170	pF	
C_{res}			40	pF	
Q_g	I _C = I _T , V _{GE} = 15 V, V _{CE} = 0.5 V _{CES}		55	nC	
Q_{ge}			13	nC	
Q_{gc}			17	nC	
t_{d(on)}	Inductive load, T_J = 25°C I _C = I _T , V _{GE} = 15 V, L = 300 μH V _{CE} = 0.8 • V _{CES} , R _G = R _{off} = 18 Ω Remarks: Switching times may increase for V _{CE} (Clamp) > 0.8 • V _{CES} , higher T _J or increased R _G		15	ns	
t_{ri}			25	ns	
t_{d(off)}			75	140	ns
t_{fi}			60	110	ns
E_{off}			0.24	0.36	mJ
t_{d(on)}		Inductive load, T_J = 125°C I _C = I _T , V _{GE} = 15 V, L = 300 μH V _{CE} = 0.8 • V _{CES} , R _G = R _{off} = 18 Ω Remarks: Switching times may increase for V _{CE} (Clamp) > 0.8 • V _{CES} , higher T _J or increased R _G		15	ns
t_{ri}			25	ns	
E_{on}			1	mJ	
t_{d(off)}			130	ns	
t_{fi}			110	ns	
E_{off}			0.6	mJ	
R_{thJC}			0.157	K/W	
R_{thCK}		0.15		K/W	

ISOPLUS 247 OUTLINE


 1 Gate, 2 Drain (Collector)
 3 Source (Emitter)
 4 no connection

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.83	5.21	.190	.205
A ₁	2.29	2.54	.090	.100
A ₂	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b ₁	1.91	2.13	.075	.084
b ₂	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	.244
R	4.32	4.83	.170	.190

Symbol	Test Conditions	Characteristic Values		
		(T _J = 25°C, unless otherwise specified)		
		min.	typ.	max.
V_F	I _F = I _T , V _{GE} = 0 V, T _J = 150°C Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 % T _J = 25°C			1.6 V 2.5 V
I_{RM}	I _F = I _T , V _{GE} = 0 V, -di _F /dt = 100 A/μs V _R = 100 V I _F = 1 A; -di _F /dt = 100 A/μs; V _R = 30 V		6	A
t_{rr}		T _J = 100°C	100	ns
		T _J = 25°C	25	ns
R_{thJC}				1.65 K/W

- Notes: 1. I_T = 24A
 2. See IXGH24N60CD1 data sheet for characteristic curves.

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